

STATUS OF THE CLAIMS

The status of the claims of the present application stands as follows:

Claim 1-16: (Canceled)

17. (Currently amended) A device, comprising:

- a)—an integrated circuit formed on a substrate and comprising a plurality of FETs wherein at least some of said plurality of FETs are finFETs each comprising:
 - i)—~~a~~ a fin having a source portion, a drain portion and a channel portion extending between said source portion and said drain portion, each of said source portion and said drain portion having an upper surface and a length extending away from said channel portion, said fin having a base portion attached to said substrate;
~~a gate located at said channel portion so as to define a first reentrant corner between said upper surface of said source portion and said gate and a second reentrant corner between said upper surface of said drain portion and said gate; and~~
 - b) a first spacer proximate said first reentrant corner and second spacer proximate said second reentrant corner, said first spacer extending a distance away from said gate in a direction along said source portion less than said length of said source portion and said second spacer extending a distance away from said gate in a direction along said drain portion a distance less than said length of said drain portion formed adjacent said base portion.

18. (Currently amended) A device according to claim ~~17~~19, further comprising a first hardmask remnant located between said ~~first~~second spacer and said upper surface of said source and a second hardmask remnant located between said ~~second~~third spacer and said upper surface of said drain.

19. (Currently amended) A device according to claim 17, wherein ~~said fin has a base portion attached to said substrate, said substrate including an undercut region located beneath at least a portion of said fin, said finFET further comprising a third spacer formed adjacent said base portion, said undercut portion containing at least a portion of said third spacer~~each of said source portion and said drain portion includes an upper surface having a width perpendicular to said length, each of said finFETs further comprising:

- a) a gate located at said channel portion;
- b) a first reentrant corner between said upper surface of said source portion and said gate;
- c) a second reentrant corner between said upper surface of said drain portion and said gate;
- d) a second spacer proximate said first reentrant corner and having a length extending along said gate substantially equal to said width of said source portion; and
- e) a third spacer proximate said second reentrant corner and having a length extending along said gate substantially equal to said width of said drain portion.

20. (Currently amended) A device according to claim 17, wherein each of said first and second spacer comprises silicon dioxide.

21. (New) A device according to claim 17, wherein said substrate comprises an undercut region beneath at least a portion of said fin, said undercut region containing at least a portion of said first spacer.

22. (New) An integrated circuit comprising:

- a) a substrate; and
- b) a plurality of FETs formed on said substrate, wherein at least some of said plurality of FETs are finFETs each comprising:
 - i) a fin having a source portion, a drain portion and a channel portion extending between said source portion and said drain portion, said fin having a base portion attached to said substrate; and
 - ii) a first spacer formed adjacent said base portion.

23. (New) An integrated circuit according to claim 22, wherein each of said source portion and said drain portion includes an upper surface having a width perpendicular to said length, each of said finFETs further comprising:

- a) a gate located at said channel portion;
- b) a first reentrant corner between said upper surface of said source portion and said gate;
- c) a second reentrant corner between said upper surface of said drain portion and said gate;
- d) a second spacer proximate said first reentrant corner and having a length extending along said gate substantially equal to said width of said source portion; and

- c) a third spacer proximate said second reentrant corner and having a length extending along said gate substantially equal to said width of said drain portion.
24. (New) An integrated circuit according to claim 23, further comprising a first hardmask remnant located between said second spacer and said upper surface of said source and a second hardmask remnant located between said third spacer and said upper surface of said drain.
25. (New) An integrated circuit according to claim 22, wherein said first spacer comprises silicon dioxide.
26. (New) An integrated circuit according to claim 22, wherein said substrate comprises an undercut region beneath at least a portion of said fin, said undercut region containing at least a portion of said first spacer.
27. (New) A finFET formed on a substrate, comprising:
- a) a fin having a source portion, a drain portion and a channel portion extending between said source portion and said drain portion, said fin having a base portion attached to the substrate; and
 - b) a first spacer formed adjacent said base portion.
28. (New) A finFET according to claim 27, wherein each of said source portion and said drain portion includes an upper surface having a width perpendicular to said length, the finFET further comprising:
- a) a gate located at said channel portion;
 - b) a first reentrant corner between said upper surface of said source portion and said gate;
 - c) a second reentrant corner between said upper surface of said drain portion and said gate;
 - d) a second spacer proximate said first reentrant corner and having a length extending along said gate substantially equal to said width of said source portion; and
 - e) a third spacer proximate said second reentrant corner and having a length extending along said gate substantially equal to said width of said drain portion.

29. (New) A finFET according to claim 28, further comprising a first hardmask remnant located between said second spacer and said upper surface of said source and a second hardmask remnant located between said third spacer and said upper surface of said drain.
30. (New) A finFET according to claim 27, wherein said first spacer comprises silicon dioxide.
31. (New) A finFET according to claim 27, wherein the substrate comprises an undercut region beneath at least a portion of said fin, the undercut region containing at least a portion of said first spacer.

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